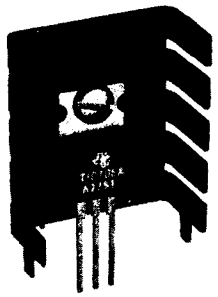
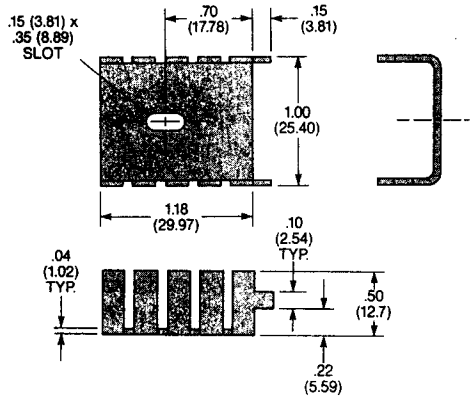
Vertically mounted heat dissipators with board mounting tabs

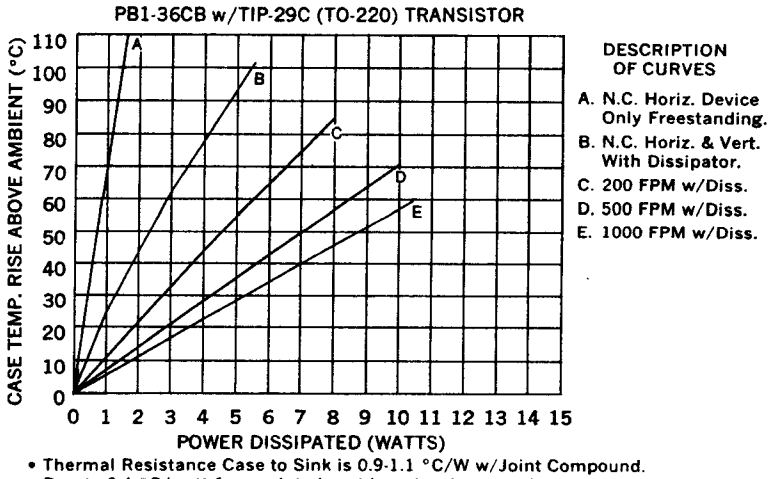
- Permits higher power levels or lower operating temperatures while occupying a minimum of valuable board space.
- Allows back-to-back dual mounting for thermal matching applications.
- Bendable tabs simplify installation to the circuit board — no mounting hardware or special tools required.
- Dissipators are available with nickel or tin finishes — allows heat sink mounting tabs to be flow-soldered onto board along with other components.
- Each dissipator is optimally designed for maximum effective surface area in a minimum working envelope.

PB1-36 Series





Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



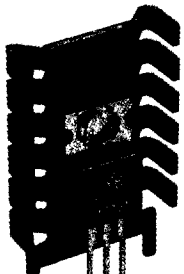
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

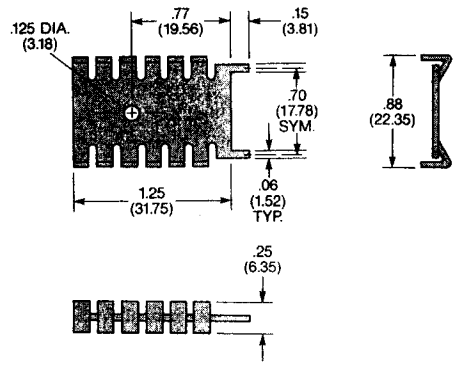
Ordering Information

IERC PART NO.					Semiconductor Accommodated	Max. Weight (Grams)
			Solderable Plating			
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Nickel	Tin		
PB1-36U	PB1-36CB	PB1-36B	PB1-36ND	PB1-36T	TO-126, TO-127, TO-220	3.9

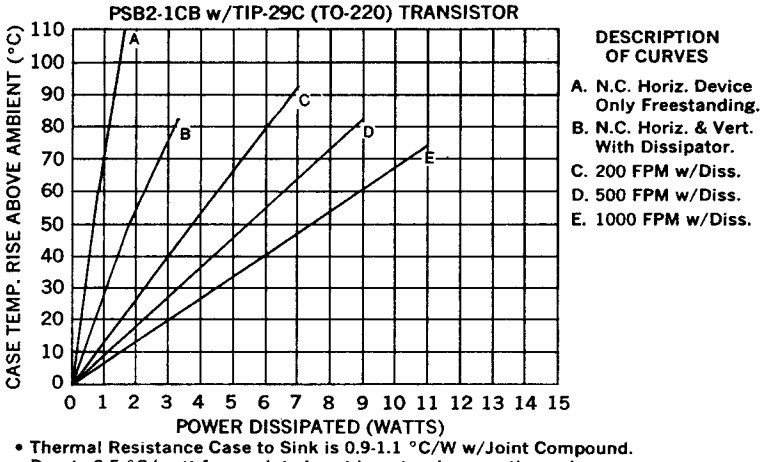
Note: See page iv for other finishes.

PSB2-1 Series





Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 3.5 °C/watt for unplated part in natural convection only.

Ordering Information

IERC PART NO.					Semiconductor Accommodated	Max. Weight (Grams)
			Solderable Plating			
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Nickel	Tin		
PSB2-1U	PSB2-1CB	PSB2-1B	PSB2-1ND	PSB2-1T	TO-126, TO-127, TO-220	2.4

Note: See page iv for other finishes.